

1. A circuit board, the circuit board characterized by comprising:
 - a substrate;
 - a first component which is mounted on said substrate by solder connection;
 - a second component which is mounted on said substrate with an anisotropic conductive film interposed therebetween; and

2. A circuit board according to claim 1, characterized in that said first component is a passive element or a mechanism component, while said second component is a semiconductor device.

4. A circuit board according to claim 1, characterized in that an alignment mark is provided outside said belt-shaped region.

6. A circuit board according to claim 1, characterized in that a plurality of said first components are disposed, and that said band-shaped region is located between the plurality of first components.

8. A circuit board according to claim 1, characterized in that said band-shaped region is disposed extending from one end to another end of said substrate.

wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first component on said substrate by the solder connection.

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